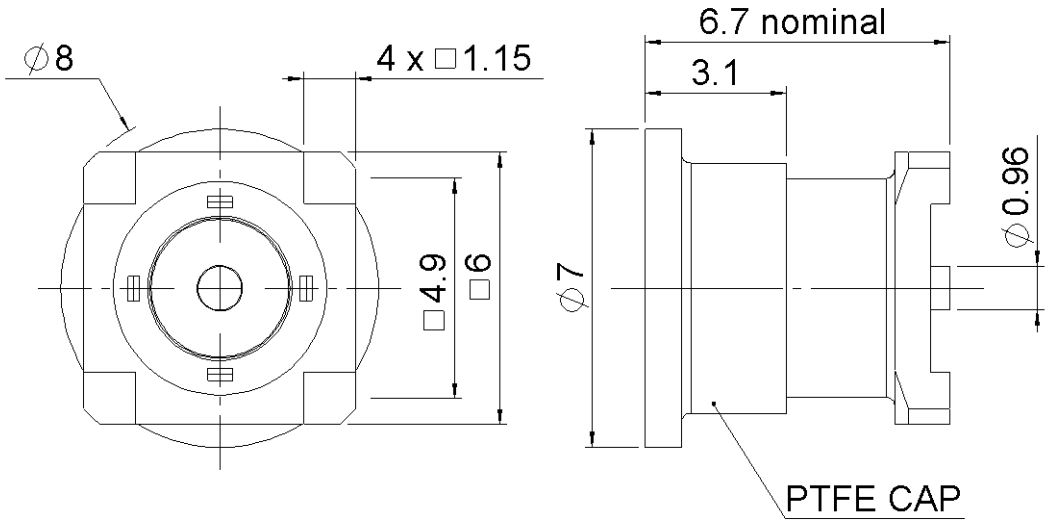
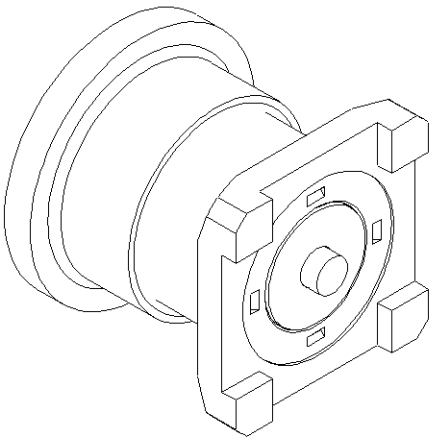
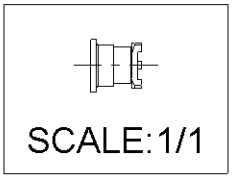
Technical Data Sheet

STRAIGHT FEMALE RECEPTACLE FOR PCB SMT TYPE - REEL OF 500

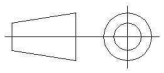
PAGE **1/5**	ISSUE **1331A**	SERIES **MCX**	PART NUMBER **R113424840**







All dimensions are in mm.



COMPONENTS	MATERIALS	PLATING (µm)
Body	**BRASS**	**GOLD OVER NICKEL**
Center contact	**BERYLLIUM COPPER**	**GOLD OVER NICKEL**
Outer contact		
Insulator	**PTFE**	
Gasket		
Others parts	**PTFE**	
-	**-**	**-**
-	**-**	**-**

PACKAGING

Standard	Unit	Other
500	**Contact us**	**Contact us**

ELECTRICAL CHARACTERISTICS

Impedance			**50**	Ω
Frequency			**0-6**	GHz
VSWR	**1.05**	**+**	**0.0500**	x F(GHz) Maxi
Insertion loss			**0.03**	√F(GHz) dB Maxi
RF leakage		- (	**NA**	- F(GHz)) dB Maxi
Voltage rating			**335**	Veff Maxi
Dielectric withstanding voltage			**1000**	Veff mini
Insulation resistance			**1000**	MΩ mini

MECHANICAL CHARACTERISTICS

Center contact retention		
Axial force – Mating End	**10**	N mini
Axial force – Opposite end	**10**	N mini
Torque	**NA**	N.cm mini
Recommended torque		
Mating	**NA**	N.cm
Panel nut	**NA**	N.cm
Mating life	**500**	Cycles mini
Weight	**0.7000**	g

ENVIRONMENTAL

Operating temperature	**-55/+155**	℃
Hermetic seal	**NA**	Atm.cm3/s
Panel leakage	**NA**	

SPECIFICATION

OTHER CHARACTERISTICS

Assembly instruction:**NA**

Others:

SOLDER PROCEDURE

1. Deposit solder paste 'Sn Ag4 Cu0.5' on mounting zone by screen printing application.
   We recommend a low residue flux. We advise a thickness of 150 microns mini. (.006 inch mini).
   Verify that the edges of the zone are clean.

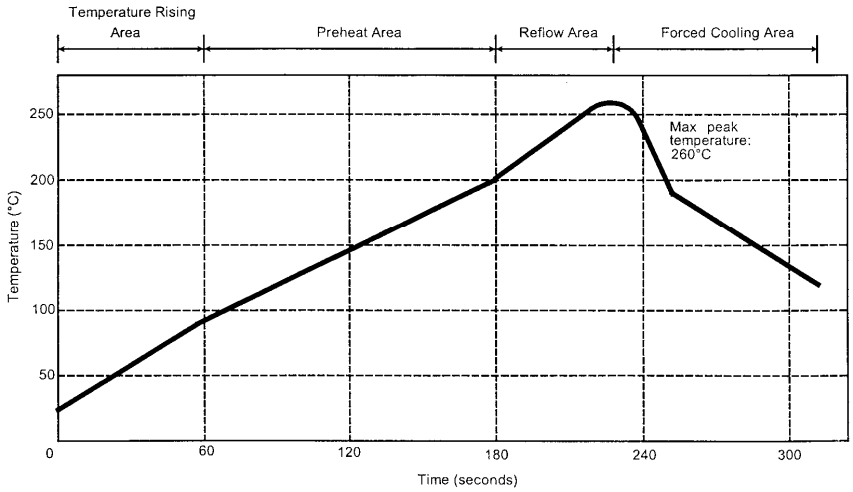
2. Placement of the receptacle on the mounting zone with an automatic machine of 'pick and place' type.
   A video camera is recommended for positioning of the component.
   Adhesive agents must not be used on the receptacle.

3. Soldering by infra-red reflow.
   Below please find the typical profile to use.

4. Cleaning of printed circuit boards.

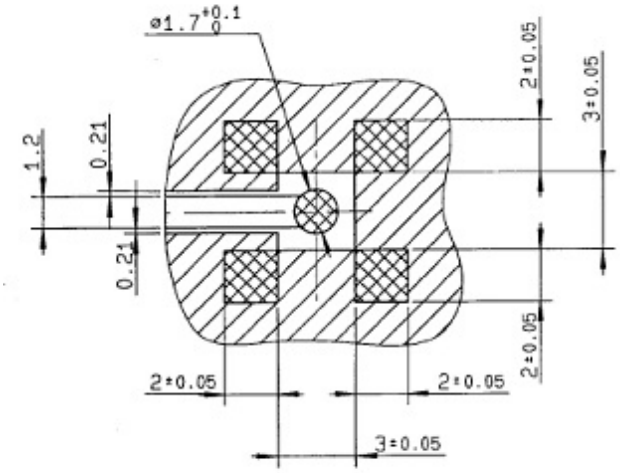
5. Verification of solder joints and position of the component by visual inspection.

TEMPERATURE PROFILE



Parameter	Value	Unit
Temperature rising Area	1 - 4	℃/sec
Max Peak Temperature	260	℃
Max dwell time @260℃	10	sec
Min dwell time @235℃	20	sec
Max dwell time @235℃	60	sec
Temperature drop in cooling Area	-1 to - 4	℃/sec
Max dwell time above 100℃	420	sec

PCB



COPLANAR LINE
Pattern and signal are on the same side
Thickness of PCB : .063 (1.6 mm)
The material of PCB is the epoxy resin
of glass fabrics bacs.(Er = 4.8)
The solder resist should be printed
exept for the land pattern on the PCB.

Pattern

Land for solder paste

NOTE: Due to the potential large variation of performance depending on PCB and line parameters, we recommend the user to process a RF analyze of the connector mounted on his PCB

Shadow of receptacle for video camera